

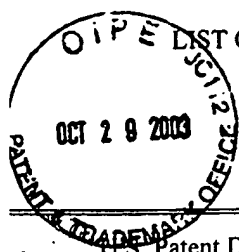
U.S. Department of Commerce, Patent and Trademark Office

Docket No.:

7135/CMP/ECP/RKK

Serial No.:

10/676,208



## LIST OF RELEVANT ART CITED BY APPLICANT

(Use several sheets if necessary)

Applicant(s):

Mei Wen et al.

Filing Date:

10/01/03

Group:

## U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
EW	AA	5,030,319	07/09/91	Nishino et al.	156	635	
	AB	5,503,878	04/02/96	Suzuki et al.	427	539	
	AC	5,814,157	09/29/98	Mizuniwa et al.	134	1.2	
	AD	5,968,279	10/19/99	MacLeish et al.	134	1.2	
	AE	5,992,729	11/30/99	Koopman et al.	228	175	
	AF	5,994,240	11/30/99	Thakur	438	758	
	AG	5,996,594	12/07/99	Roy et al.	134	1.3	
	AH	6,033,584	03/07/00	Ngo et al.	216	67	
	AI	6,040,021	03/21/00	Miyamoto	427	576	
	AJ	6,107,192	08/22/00	Subrahmanyam et al.	438	637	
	AK	6,117,570	09/12/00	Chen et al.	428	694T	

## Foreign Patent Documents

## Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
EW	AL	JP04131395 A	05/06/92	Japan			X abstract only	
	AM	JP2000208444 A	07/28/00	Japan			X abstract only	
	AN	WO 97/15173	04/24/97	WIPO				
	AO	WO 02/45155 A2	06/06/02	WIPO				
	AP	WO 02/068727 A2	09/06/02	WIPO				

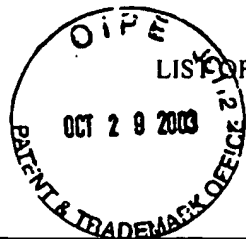
## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

EW	AR	U.S. Patent Application No. US 2002/0088713 A1, Pub. Date: July 11, 2002
EW	AS	U.S. Patent Application No. US 2002/0001860 A1, Pub. Date: January 3, 2002
EW	AT	U.S. Patent Application No. US 2002/0011415 A1, Pub. Date: January 31, 2002

Examiner /Edna Wong/	Date Considered 02/21/2007
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

## U.S. Department of Commerce, Patent and Trademark Office



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October 1, 2003

Group:

## U.S. Patent Documents

*Examiner Initial		Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
EW	AA	6,132,564	10/17/00	Licata	204	192.15	
	AB	6,277,749 B1	08/21/01	Funabashi	438	689	
	AC	6,284,649 B1	09/04/01	Miyamoto	438	643	
	AD	6,319,616 B1	11/20/01	Lopatin et al.	428	469	
	AE	6,319,728 B1	11/20/01	Bhan et al.	436	687	
	AF	6,346,489 B1	02/12/02	Cohen et al.	438	789	
	AG	6,395,642 B1	05/28/02	Liu et al.	438	720	
	AH	6,420,261 B2	07/16/02	Kudo	438	633	
	AI	6,582,578 B1	06/24/03	Dordi et al.	205	80	
	AJ	6,613,663 B2	09/02/03	Furuya	438	613	
	AK	5,932,022	08/03/99	Linn et al.	134	3	

## Foreign Patent Documents

## Translation

		Document Number	Date	Country	Class	Subclass	Yes	No
EW	AL	WO 03/005437 A2	01/16/03	WIPO	—	—		
	AM							
	AN							
	AO							
	AP							

## OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

EW	AR	U.S. Patent Application No. US 2002/0076929 A1, Pub. Date: June 20, 2002
	AS	U.S. Patent Application No. US 2002/0134684 A1, Pub. Date: September 26, 2002
	AT	U.S. Patent Application No. US 2003/0176064 A1, Pub. Date: September 18, 2003
	AU	Lu, et al., Understanding and Eliminating Defects in Electroplated Cu Films, 2001, pgs. 280-282 no month

Examiner

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Date Considered

02/21/2007

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